jc836 U.S. PTO 09/648777 08/28/00

Subclass	ISSUE CLASSIFICATION
Class	

PATENT NUMBER

U.S. UTILITY Patent Application

O.I.P.E.	PATENT DATE
SCANNED Am Q.A. A.G.	

APPLICATION NO.	CONT/PRIOR	CLASS	SUBCLASS	ART UNIT	EXAMINER
09/648777	D	~~428/627~~ 438	~~372~~ 612	~~1775~~ 2812	~~Talbot~~ Nguyen, Ha

WGW

APPLICANTS: Song-Hua Shi
Ching-Ping Wong

TITLE OF INVENTION: Process and material for low-cost flip-chip solder interconnect structures

PTO-2040
12/99

ISSUING CLASSIFICATION

ORIGINAL		CROSS REFERENCE(S)	
CLASS	SUBCLASS	CLASS	SUBCLASS (ONE SUBCLASS PER BLOCK)
INTERNATIONAL CLASSIFICATION			

☐ Continued on Issue Slip Inside File Jacket

☐ TERMINAL DISCLAIMER	DRAWINGS			CLAIMS ALLOWED	
	Sheets Drwg.	Figs. Drwg.	Print Fig.	Total Claims	Print Claim for O.G.
☐ The term of this patent subsequent to _____ (date) has been disclaimed.				NOTICE OF ALLOWANCE MAILED	
☐ The term of this patent shall not extend beyond the expiration date of U.S Patent. No. _____				ISSUE FEE	
				Amount Due	Date Paid
☐ The terminal ____months of this patent have been disclaimed.				ISSUE BATCH NUMBER	

(Assistant Examiner) (Date)

(Primary Examiner) (Date)

(Legal Instruments Examiner) (Date)

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